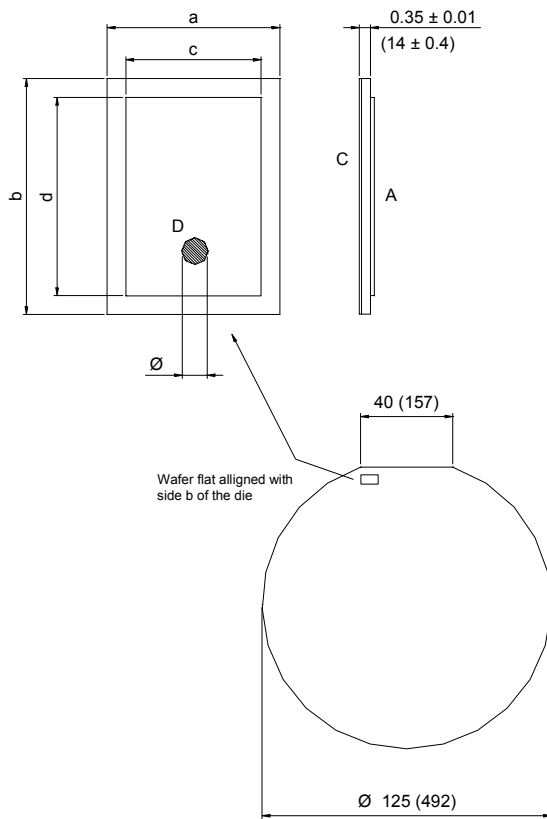


SCHOTTKY DIE 105 x 125 mils



NOTES:

1. ALL DIMENSIONS ARE SHOWN IN MILLIMETERS (MILS).
2. CONTROLLING DIMENSION: (MILS).
3. DIMENSIONS AND TOLERANCES:
 - $a = 3.18 + 0, - 0.01$
(125 + 0, - 0.4)
 - $b = 2.67 + 0, - 0.01$
(105 + 0, - 0.4)
 - $c = 3.02 + 0, - 0.01$
(119 + 0, - 0.4)
 - $d = 2.51 + 0, - 0.01$
(99 + 0, - 0.4)
 - $\varnothing = 1 \pm 0.15$
(40 ± 6)
4. LETTER DESIGNATION:
 - A = Anode (Top Metal)
 - C = Cathode (Back Metal)
 - D = Reject Ink Dot (only on non-conforming dies)
5. SAWING:
 - Recommended Blade
 - SEMITEC S1025 QS00 Blade
 - Sawing Street
 - $0.05 + 0, - 0.005$
(2 + 0, - 0.2)

NOT TO SCALE

NOTE: 10 mils die thickness is available on specific request only.
 Contact factory for information.

Electrical Characteristics

Device #	T _J Max. (°C)	V _R (V)	Typ. I _R @ 25°C (µA)	Typ. I _R @ 125°C (mA)	Max. V _F @ I _F (V)	Package Style
SC105R015x5x	125	15	n.a. contact factory			
SC105S020x5x	150	20	700	180	0.51 @ 40A	TO-220
SC105S030x5x	150	30	220	100	0.49 @ 15A	TO-220
SC105S045x5x	150	45	150	75	0.54 @ 15A	TO-247
SC105S060x5x	150	60	110	60	0.60 @ 15A	TO-247
SC105H045x5x	175	45	35	10	0.62 @ 15A	TO-220
SC105H100x5x	175	100	12	7	0.86 @ 15A	TO-247
SC105H150x5x	175	150	15	10	1.0 @ 15A	TO-220

Mechanical Data

Device #		Metal Thickness Front Metal			Metal Thickness Back Metal		
SC105xxxxA5x	Bondable	–	Al/Si 30 kÅ	–	Cr 1 kÅ	Ni 2 kÅ	Ag 3 kÅ
SC105xxxxS5x	Solderable	Ti 2 kÅ	Ni 1 kÅ	Ag 35 kÅ	Cr 1 kÅ	Ni 2 kÅ	Ag 3 kÅ

Recommended Storage Environment: Store in original container, in dessicated nitrogen, with no contamination.

Shelf life for parts stored in above condition is 2 years.

If the storage is done in normal atmosphere shelf life is reduced to six months.

Packaging

Device #	Description	Minimum Order Quantity Die in Sale Package
SC105xxxx5B	Inked Probed Unsawn Wafer (Wafer in Box)	1170
SC105xxxx5R	Probed Die in Tape & Reel	8,000
SC105xxxx5P	Probed Die in Waffle Pack	1170
SC105xxxx5F	Inked Probed Sawn Wafer on Film	1170

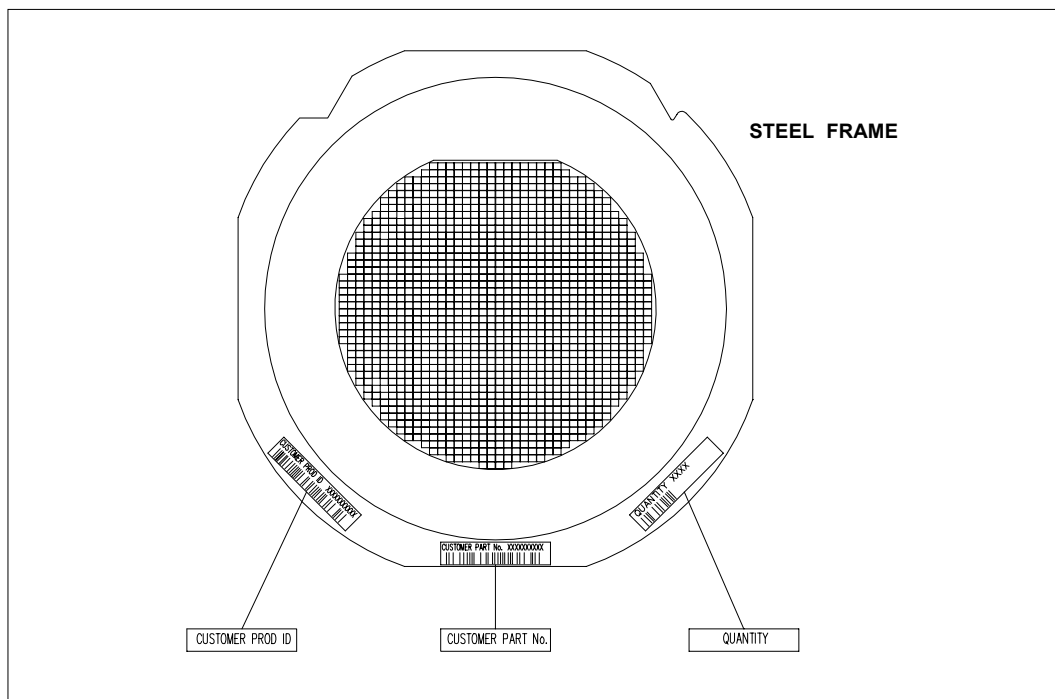
Ordering Information Table

Device Code						
SC	105	H	100	S	5	B
①	②	③	④	⑤	⑥	⑦

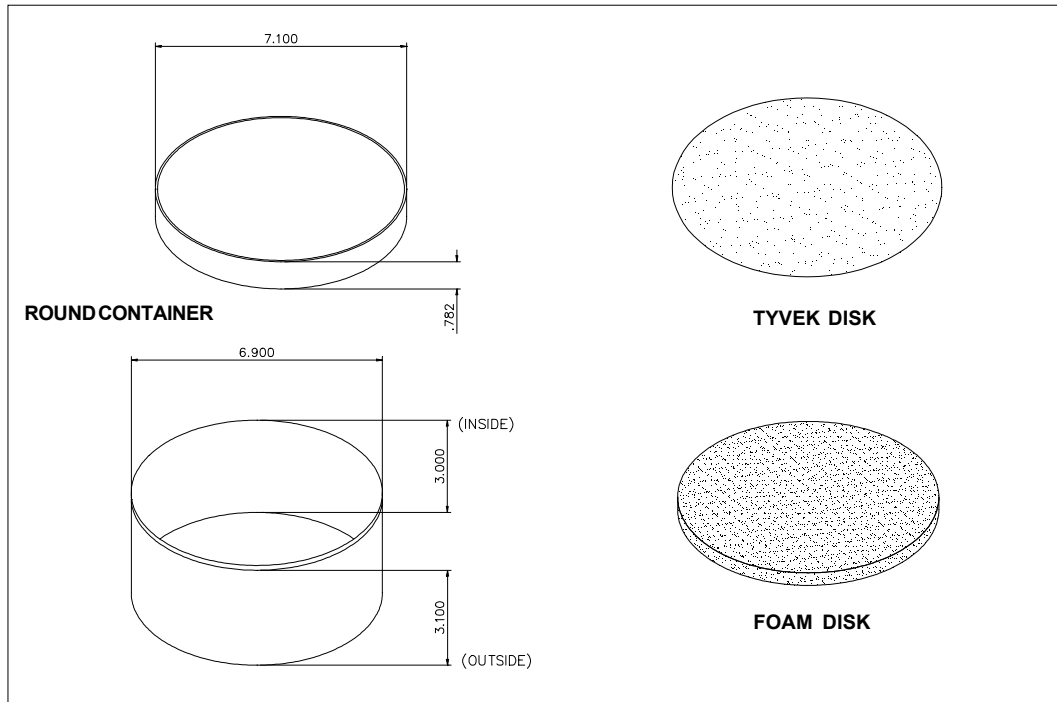
- 1** - Schottky Die
- 2** - Chip Dimension in Mils
- 3** - Process (see Electrical Characteristics Table)
- 4** - Voltage code: Code = V_{RRM}
- 5** - Chip surface metallization (see Mechanical Data Table)
- 6** - Wafer Diameter in inches
- 7** - Packaging (see Packaging Table)

H = 830 Process
 R = OR'ing Process
 S = Standard Process

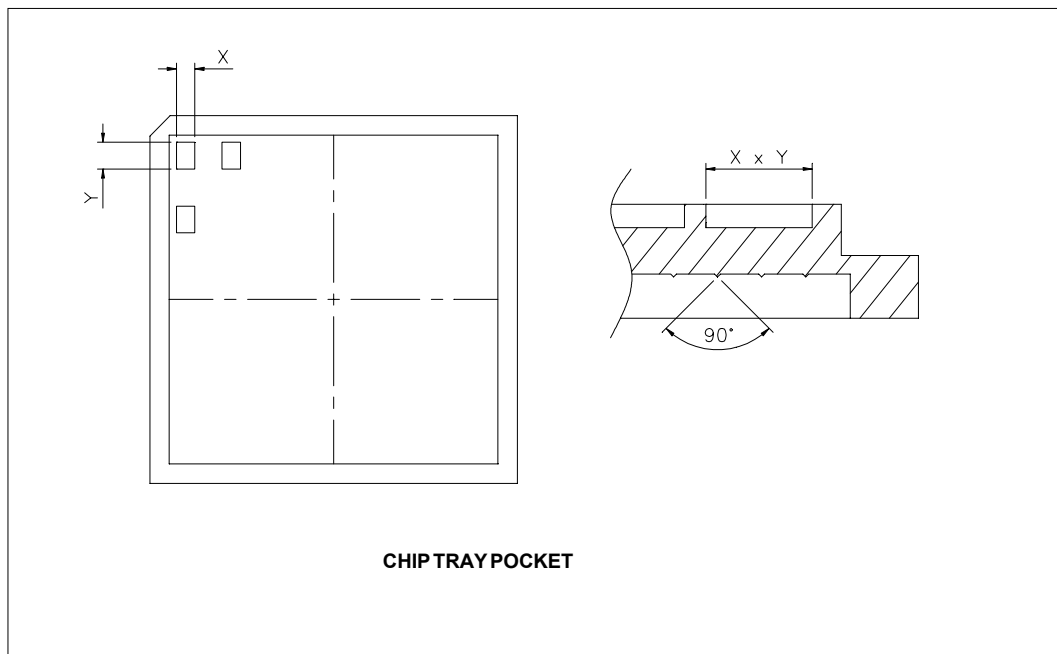
Wafer on Film



Wafer in Box



Die in Waffle Pack



Tape and Reel

